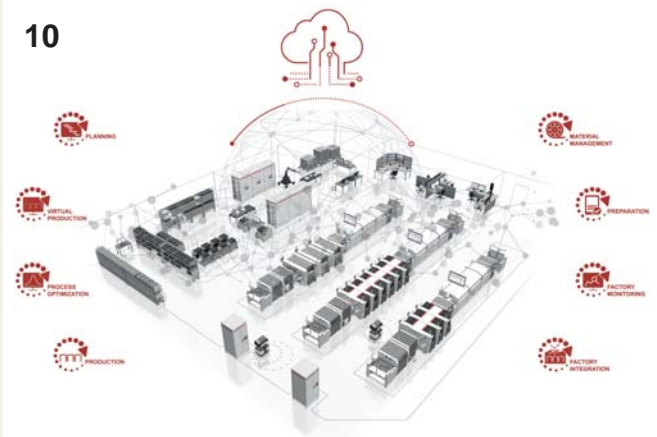


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ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@dempa.co.jp;

Subscription e-mail: circulationmanila@dempa.co.jp. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <https://www.dempa.co.jp/en/pdfs/orderform.pdf>

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**TAIWAN:** International Dempa Trade Co. Ltd., 7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559 **KOREA:** Dempa Publications, Room 1019, Punglim VIP Tel, 404, Gongdeuk-dong, Mapo, Seoul, Korea 04144, Tel: +82-2-714-2983 Fax: +82-2-714-2984 **PHILIPPINES:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tsutomu Hirayama  
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